

PSM15065H

650V 15A 260mΩ Si Super junction MOSFET with Normal body diode

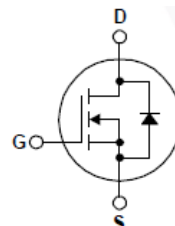
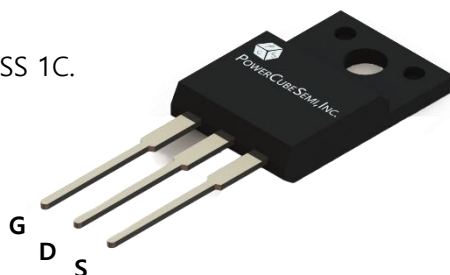
Features

Si Super junction MOSFET

- Rated to 650V at 15Amps @ $T_C = 25^\circ\text{C}$
- Max $R_{DS(on)} = 260\text{ m}\Omega$
- Typ $R_{DS(on)} = 230\text{ m}\Omega$
- Gate Charge(Typ. $Q_g=30\text{ nC}$)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Thin Wafer Technology applied
- The ESD protection class is CLASS 1C.

Application

- LCD/LED/PDP TV
- Telecom/Server Power supplies
- AC-DC Power Supply
- LED Lighting



PKG type : TO-220F

Description

PSM15065H is PowerCubeSemi's second generation of high voltage Super Junction MOSFET that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, the combination of Super Junction MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency

Absolute Maximum Ratings

Symbol	Parameter	Test Condition	Value	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	650	V
I_D	Drain Current	$T_C=25^\circ\text{C}$	15	A
I_{DM}	Pulsed Drain Current	Pulse width limited by junction temperature	40	A
V_{GS}	Gate-Source Voltage		± 20	V
E_{AS}	Single Pulsed Avalanche Energy	$I_{AS}=7.5A, R_G=25\Omega$ $V_{DD}=50V, L=20mH$	530	mJ
P_d	Power Dissipation	$T_C=25^\circ\text{C}$	39	W
T_J	Operating Junction Temperature		150	$^\circ\text{C}$
T_{stg}	Storage Temperature		-55 to 150	$^\circ\text{C}$



Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PSM15065H	PSM15065	TO-220F	TUBE	-	50

Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
BV_{DSS}	Drain-source breakdown voltage	$V_{GS} = 0V, I_D = 1mA, T_C = 25^\circ C$	650	-	-	V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 650V, V_{GS} = 0V$	-	-	10	μA
I_{GSS}	Gate-source leakage current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 1mA$	3.5	-	4.5	V
$R_{DS(ON)}$	Static drain-source on state resistance	$V_{GS} = 10V, I_D = 7.5A$	-	230	260	m Ω
$t_{d(on)}$	Turn-on Delay time	$V_{DD} = 380V, I_D = 7.5A, V_{GS} = 10V, R_G = 4.7\Omega$	-	18	-	ns
T_r	Turn-on Rise time		-	7	-	
$t_{d(off)}$	Turn-off Delay time		-	51	-	
T_f	Turn-off Fall time		-	14	-	



Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$R_{\theta JC}$	Thermal resistance, Junction to case		3.2		$^{\circ}\text{C}/\text{W}$
R_g	Gate resistance	$V_{GS} = 0\text{V}$, $f = 1\text{MHz}$	6	8	Ω
C_{iss}	Input capacitance	$V_{DS} = 380\text{V}$, $V_{GS} = 0\text{V}$, $F = 1\text{MHz}$	1500	-	pF
C_{oss}	Output capacitance		35	-	
C_{rss}	Reverse transfer capacitance		1.5	-	
$Q_{g(tot)}$	Total gate charge at 10V	$V_{DS} = 380\text{V}$, $I_D = 15\text{A}$ $V_{GS(on)} = 10\text{V}$	30	-	nC
Q_{gs}	Gate to source gate charge		5.3	-	
Q_{gd}	Gate to drain "Miller" charge		12	-	

Electrical Characteristics of Si Diode

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
I_S	Maximum continuous drain to source diode forward current		-	15	A
I_{SM}	Maximum pulsed drain to source diode forward current		-	40	A
V_{SD}	Drain to source diode forward voltage	$I_{SD} = 15\text{A}$, $V_{GS} = 0\text{V}$	-	1.2	V
T_{rr}	Reverse recovery time	$I_{SD} = 7.5\text{A}$, $V_{DD} = 400\text{V}$, $di_F/dt = 100\text{A}/\mu\text{s}$	260	-	ns
Q_{rr}	Reverse recovery charge		3.2	-	μC
I_{rrm}	Reverse recovery current		24		A

Typical Characteristics

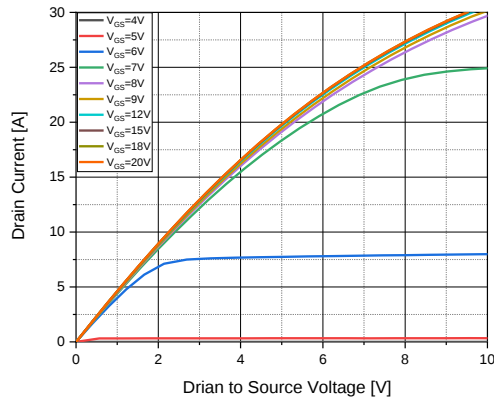


Figure 1. On-state characteristics

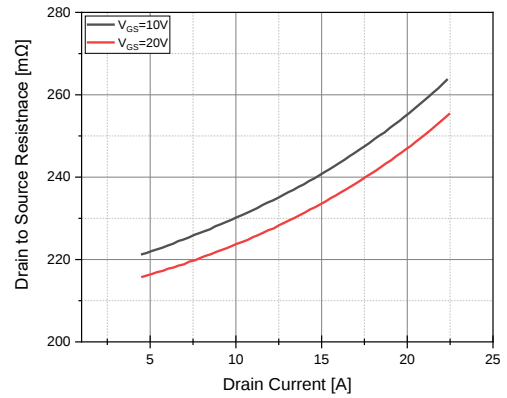


Figure 2. On resistance variation vs Drain current and gate voltage

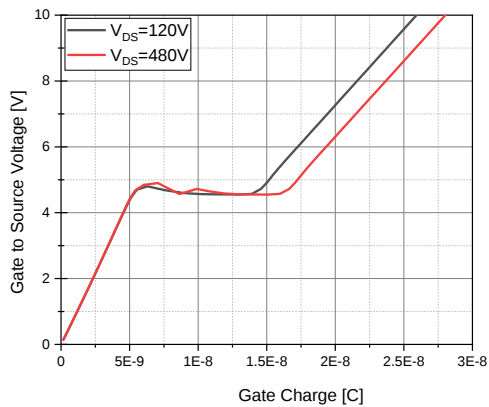


Figure 3. Gate charge characteristics

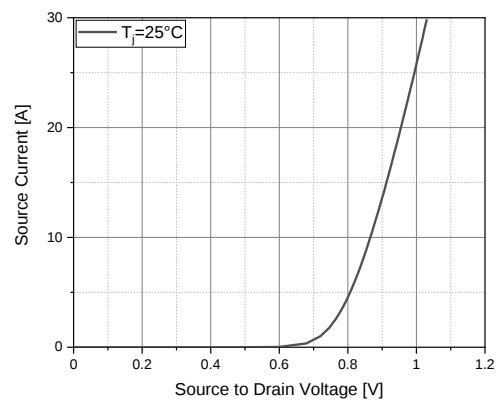


Figure 4. On-state current vs Diode forward voltage

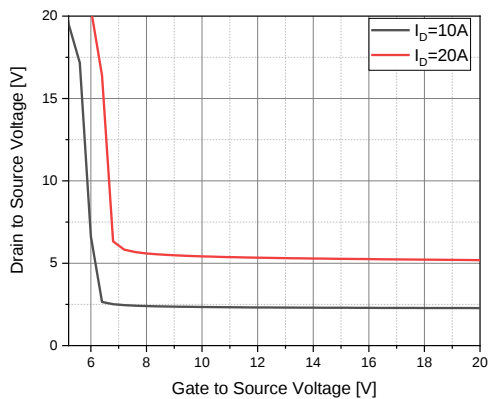


Figure 5. Drain to source voltage vs Gate to Source voltage

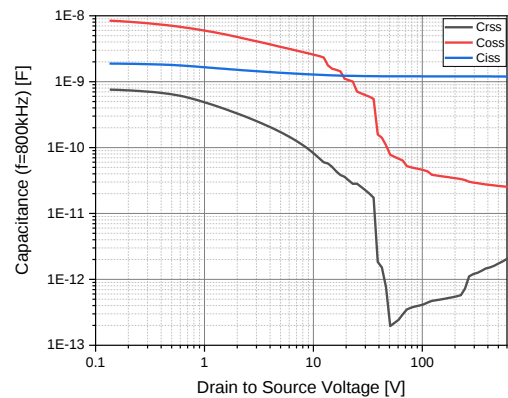


Figure 6. Capacitance characteristics

Typical Characteristics

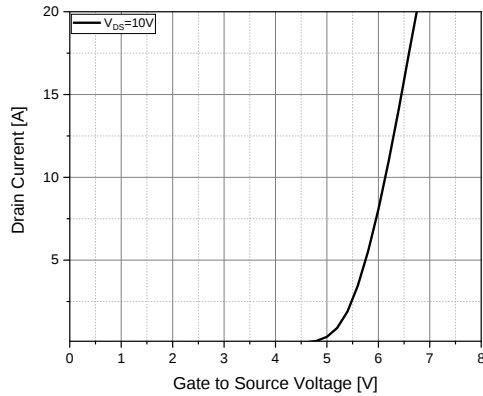


Figure 7. Transfer characteristics

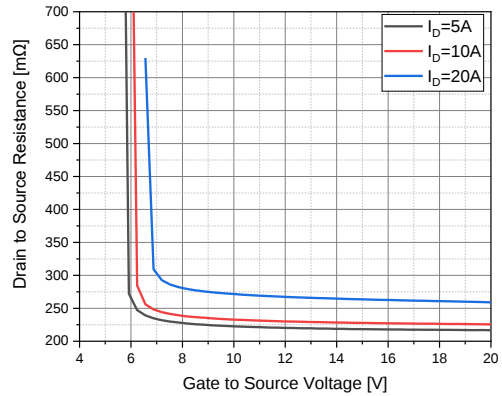
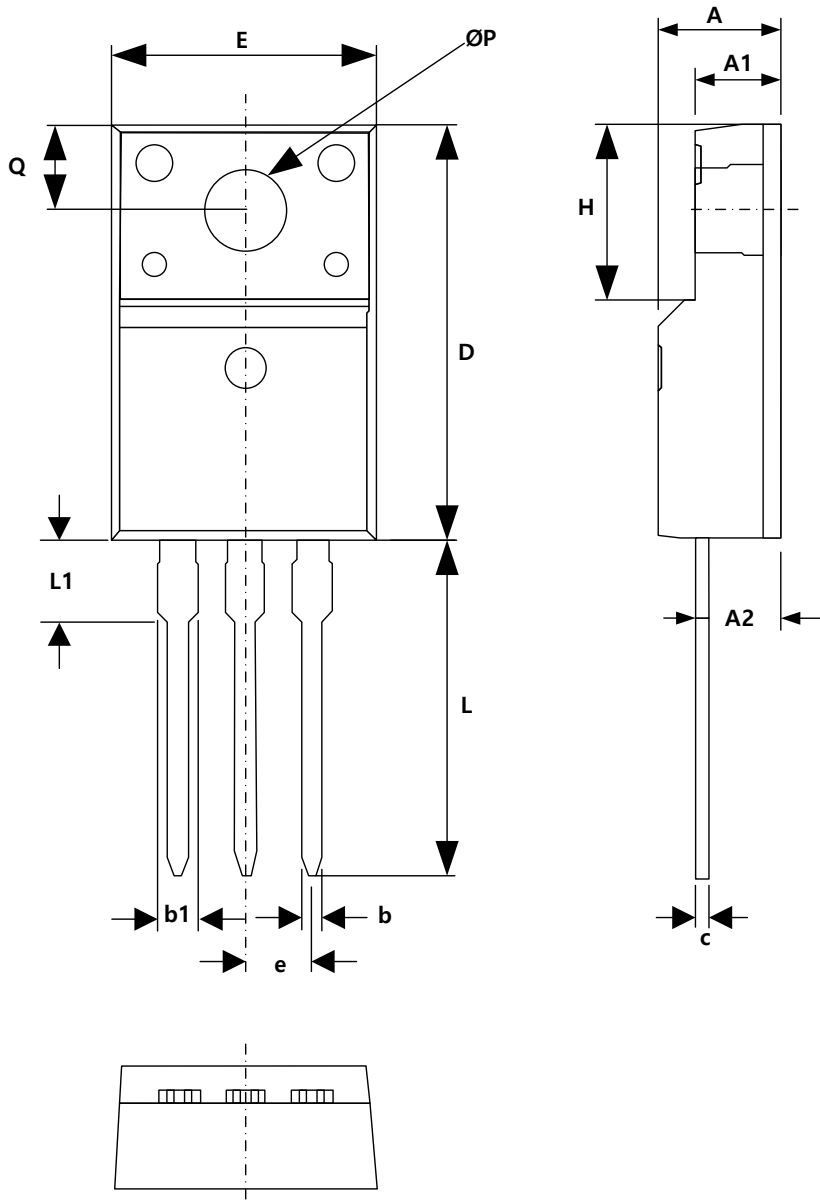


Figure 8. Drain to source resistance vs Gate to source voltage



Package Outline

[Unit : mm]



SYMBOL	DIMENSIONS	
	MIN	MAX
A	4.50	4.90
A1	2.34	2.74
A2	2.56	2.96
b	0.70	0.90
b1	1.27	1.47
c	0.45	0.60
D	15.67	16.07
E	9.96	10.36
e	2.54 BSC	
H	6.48	6.88
L	12.68	13.28
L1	3.03	3.43
ϕP	3.08	3.28
Q	3.20	3.40